

PACKAGE MATERIAL LIST

item #	material	thickness	thermal conductivity
leadframe	copper	0.15 mm	3.9 W/cm°C
die attach	silver glue	10-40 μ m	0.01 W/cm°C
molding compound	epoxy resin	1.4 mm	0.0063W/cm°C

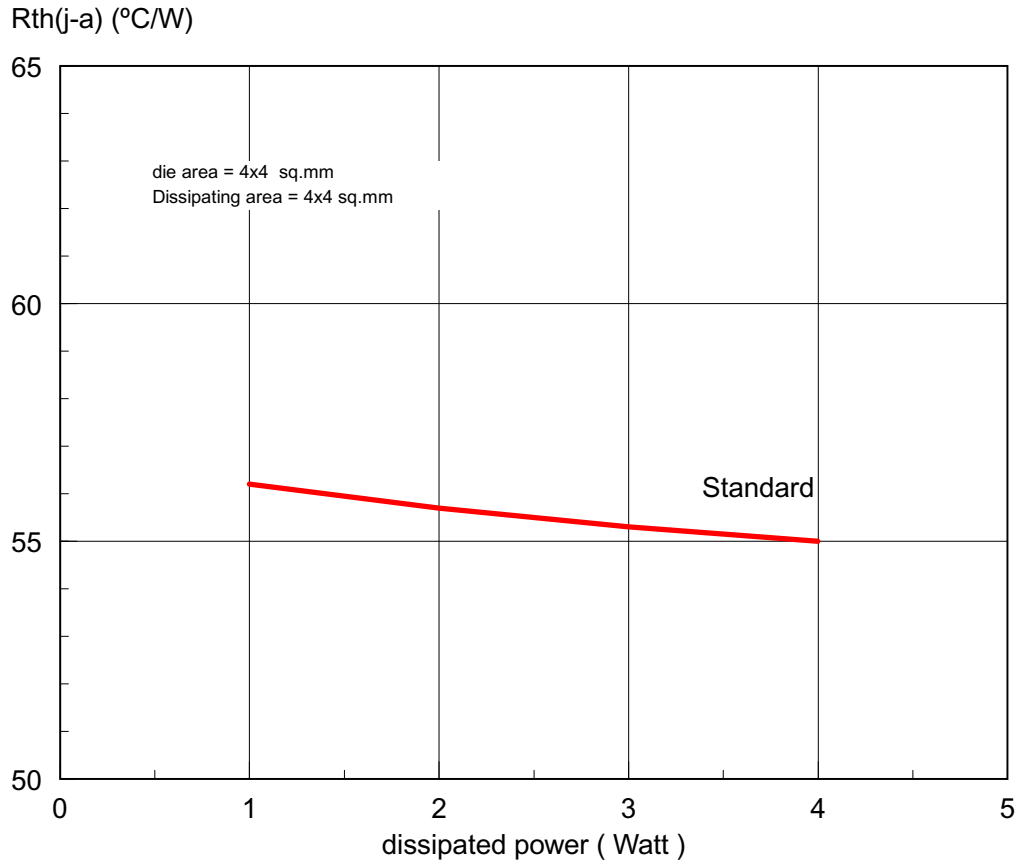
Frame options :

i) standard frame

Charts enclosed :

- 1) $R_{th}(j-a)$ vs on board heat sink area
- 2) $Z_{th}(j-a)$ vs time width

1)



2)

